

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- High Efficiency
- High Current Capability
- High Reliability
- High Surge Current Capability
- Low Power Loss
- Glass Passivated Chip Junction
- Solder Dip, Per JESD 22-B106

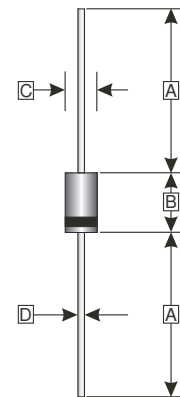
MECHANICAL DATA

- Molding Compound Meets UL 94 V-0 Flammability Rating
- Terminals: Tin Plated Leads, Solderable Per J-STD-002 and JESD22-B102
- Polarity: Color Band Denotes Cathode End

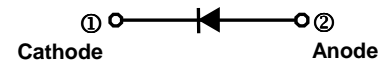
ORDER INFORMATION

Part Number	Type
RL251G~RL257G	Lead (Pb)-free
RL251G-C~RL257G-C	Lead (Pb)-free and Halogen-free

DO-15



REF.	Millimeter	
	Min.	Max.
A	25.4 (TYP)	
B	5.80	7.62
C	2.60	3.60
D	-	0.90



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Part Number							Unit
		RL 251G	RL 252G	RL 253G	RL 254G	RL 255G	RL 256G	RL 257G	
Repetitive Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Average Forward Current @60Hz Sine Wave, Resistance Load, T _L =80°C	I _{F(AV)}	2.5							A
Surge(Non-Repetitive)Forward Current @60Hz Half-Sine Wave, 1 Cycle, T _A =25°C	I _{FSM}	120							A
Maximum Instantaneous Forward Voltage Drop Per Diode @I _{FM} =2.5A	V _{FM}	1.1							V
Maximum DC Reverse Current @Rated DC Blocking Voltage Per Diode	T _A =25°C	2.5							μA
	T _A =125°C	50							
Typical Junction Capacitance ¹	C _J	35							pF
Typical Thermal Resistance from Junction-Ambient	R _{θJA}	45							°C/W
Typical Thermal Resistance from Junction-Lead	R _{θJL}	28							°C/W
Junction and Storage Temperature Range	T _J , T _{STG}	-55~150							°C

Note:

1. Measured at 1MHz and applied reverse voltage of 4V D.C.

RATINGS AND CHARACTERISTIC CURVES

FIG.1: I_o-T_a Curve

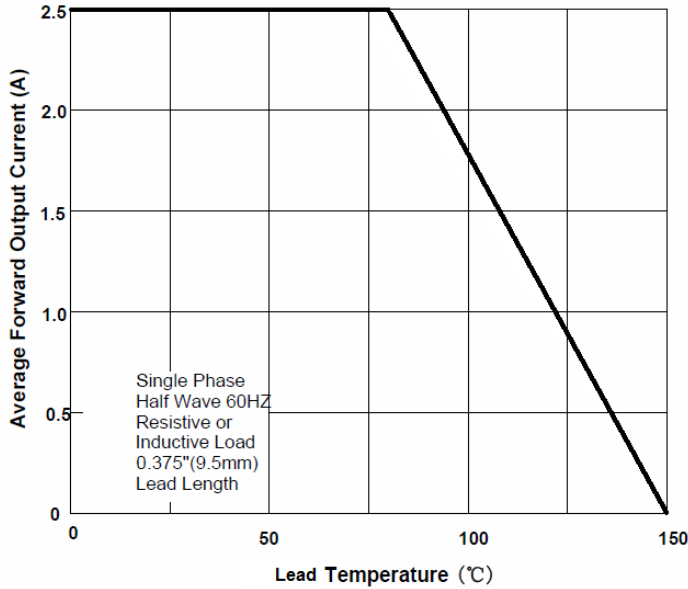


FIG.2: Surge Forward Current Capability

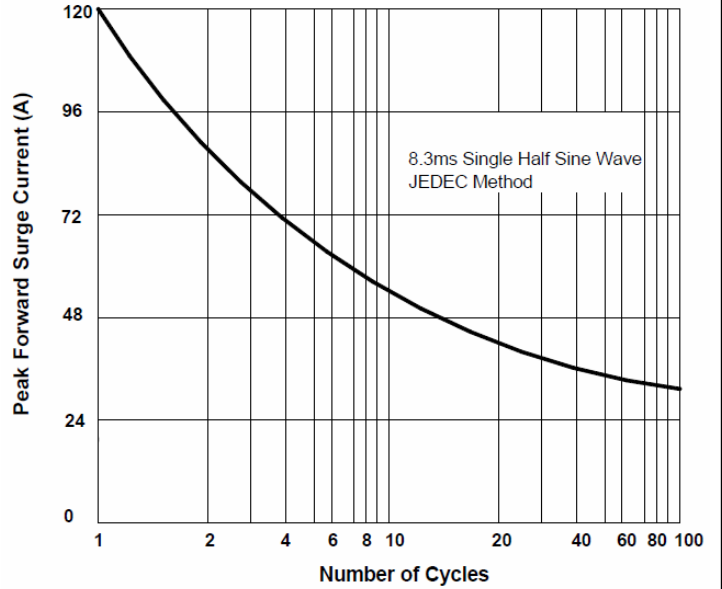


FIG.3: Forward Voltage

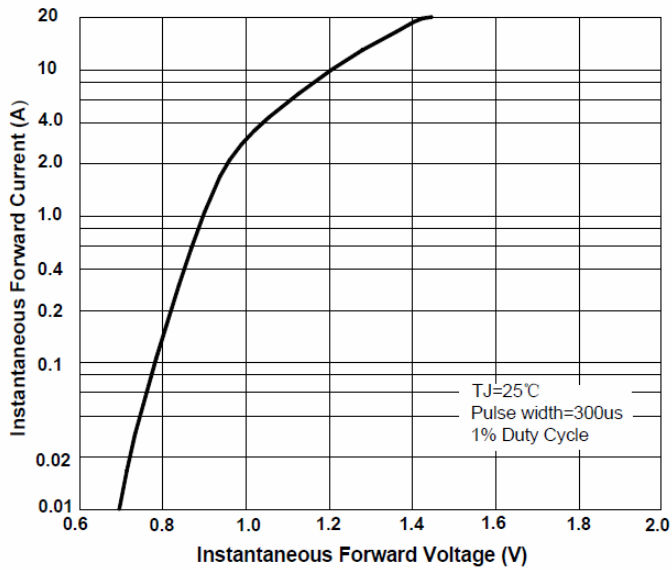


FIG.4: Typical Reverse Characteristics

